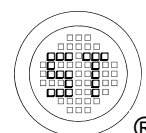


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Characteristics at $T_a = 25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit
STATIC PARAMETERS					
Drain-Source Breakdown Voltage at $I_D = 250 \mu\text{A}$	$V_{(BR)DSS}$	30	-	-	V
Zero Gate Voltage Drain Current at $V_{DS} = 24 \text{ V}$	I_{DSS}	-	-	1	μA
Gate-Source Leakage at $V_{GS} = \pm 12 \text{ V}$	I_{GSS}	-	-	± 100	nA
Gate-Source Threshold Voltage at $V_{GS} = V_{DS}, I_D = 250 \mu\text{A}$	$V_{GS(th)}$	0.65	-	1.45	V
Drain-Source On-State Resistance at $V_{GS} = 10 \text{ V}, I_D = 5.8 \text{ A}$ at $V_{GS} = 4.5 \text{ V}, I_D = 5 \text{ A}$ at $V_{GS} = 2.5 \text{ V}, I_D = 4 \text{ A}$	$R_{DS(on)}$	- - -	- - -	28 33 52	$\text{m}\Omega$
DYNAMIC PARAMETERS					
Gate Resistance at $V_{DS} = 0 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	R_g	-	5.9	-	Ω
Forward Transconductance at $V_{DS} = 5 \text{ V}, I_D = 5 \text{ A}$	g_{fs}	-	12	-	S
Input Capacitance at $V_{GS} = 0 \text{ V}, V_{DS} = 15 \text{ V}, f = 1 \text{ MHz}$	C_{iss}	-	505	-	pF
Output Capacitance at $V_{GS} = 0 \text{ V}, V_{DS} = 15 \text{ V}, f = 1 \text{ MHz}$	C_{oss}	-	61	-	pF
Reverse Transfer Capacitance at $V_{GS} = 0 \text{ V}, V_{DS} = 15 \text{ V}, f = 1 \text{ MHz}$	C_{rss}	-	50	-	pF
Total Gate Charge at $V_{DS} = 15 \text{ V}, I_D = 4.2 \text{ A}, V_{GS} = 10 \text{ V}$ at $V_{DS} = 15 \text{ V}, I_D = 4.2 \text{ A}, V_{GS} = 4.5 \text{ V}$	Q_g	- -	11.5 5.3	- -	nC
Gate to Source Charge at $V_{DS} = 15 \text{ V}, I_D = 4.2 \text{ A}, V_{GS} = 10 \text{ V}$	Q_{gs}	-	1.4	-	nC
Gate to Drain Charge at $V_{DS} = 15 \text{ V}, I_D = 4.2 \text{ A}, V_{GS} = 10 \text{ V}$	Q_{gd}	-	1.6	-	nC
Turn-On Delay Time at $V_{DD} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 1 \text{ A}, R_g = 1 \Omega$	$t_{d(on)}$	-	7	-	nS
Turn-On Rise Time at $V_{DD} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 1 \text{ A}, R_g = 1 \Omega$	t_r	-	3.6	-	nS
Turn-Off Delay Time at $V_{DD} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 1 \text{ A}, R_g = 1 \Omega$	$t_{d(off)}$	-	12	-	nS
Turn-Off Fall Time at $V_{DD} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 1 \text{ A}, R_g = 1 \Omega$	t_f	-	5	-	nS
Body-Diode PARAMETERS					
Drain-Source Diode Forward Voltage at $V_{GS} = 0 \text{ V}, I_S = 1 \text{ A}$	V_{SD}	-	-	1	V
Body-Diode Continuous Current	I_S	-	-	5.8	A
Body Diode Reverse Recovery Time at $I_S = 1 \text{ A}, di/dt = 100 \text{ A} / \mu\text{s}$	t_{rr}	-	7.4	-	nS
Body Diode Reverse Recovery Charge at $I_S = 1 \text{ A}, di/dt = 100 \text{ A} / \mu\text{s}$	Q_{rr}	-	2.2	-	nC



Electrical Characteristics Curves

Fig. 1 Typical Output Characteristics

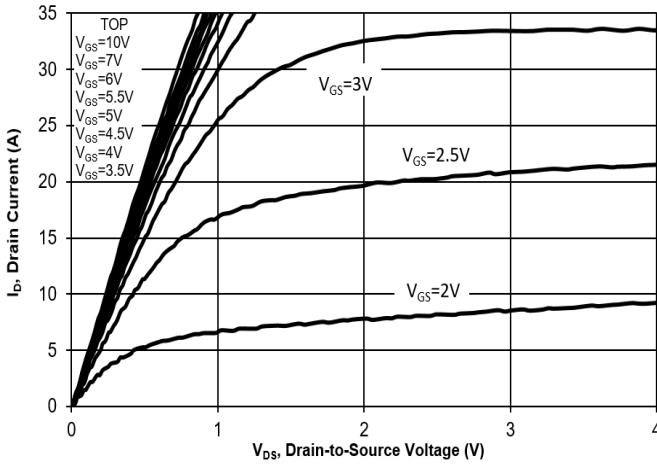


Fig. 2 Typical Transfer Characteristics

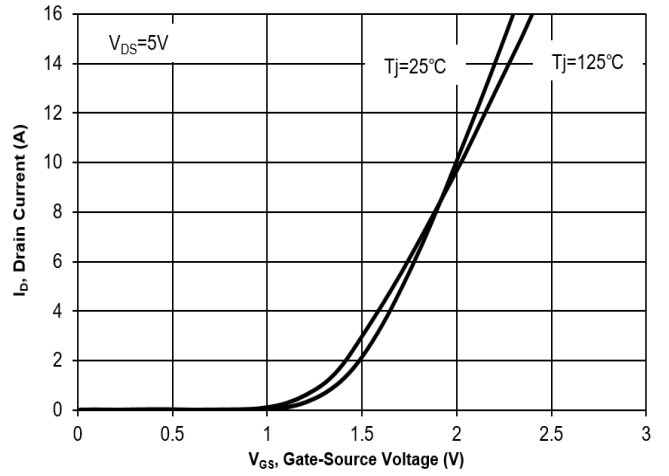


Fig. 3 on-Resistance vs. Drain Current

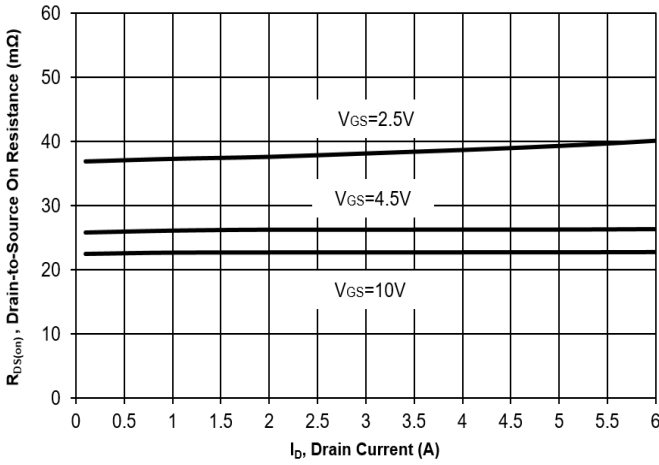


Fig. 4 on-Resistance vs. Gate to Source Voltage

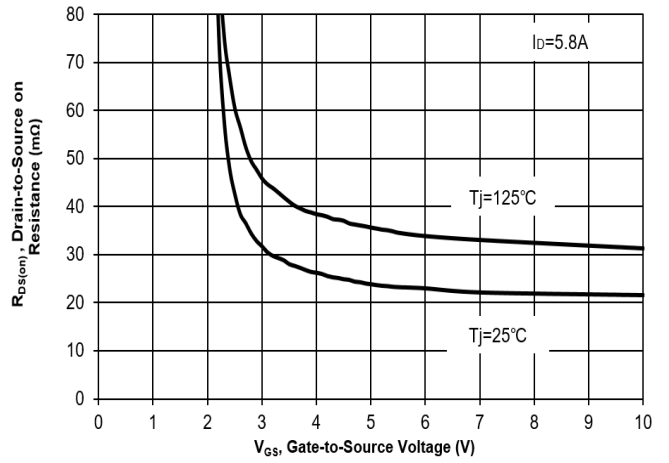


Fig. 5 on-Resistance vs. T_J

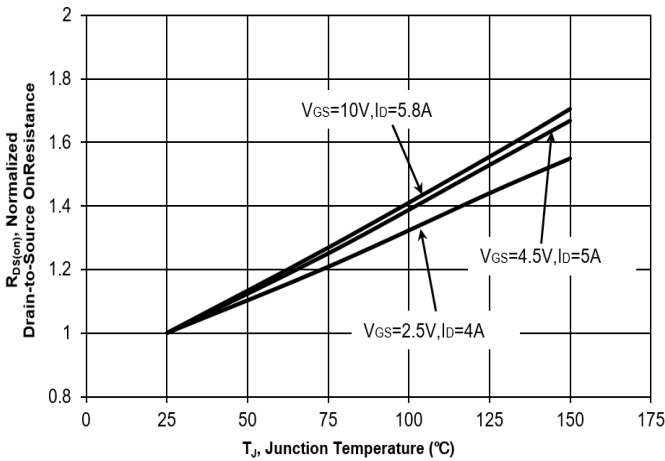
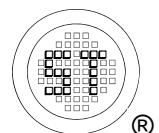
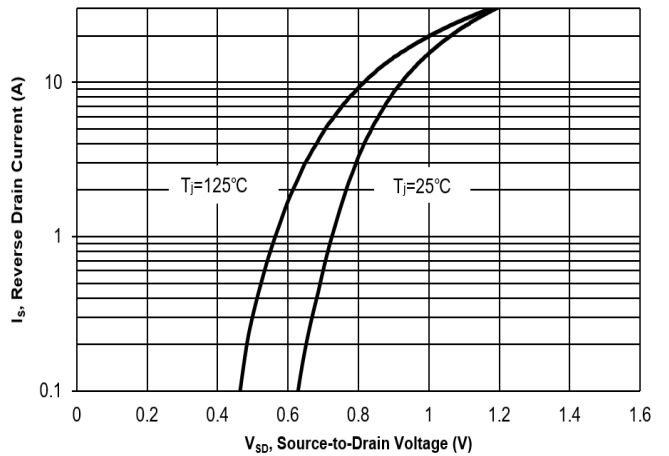


Fig. 6 Body Diodes Forward Characteristics



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Electrical Characteristics Curves

Fig. 7 Typical Junction Capacitance

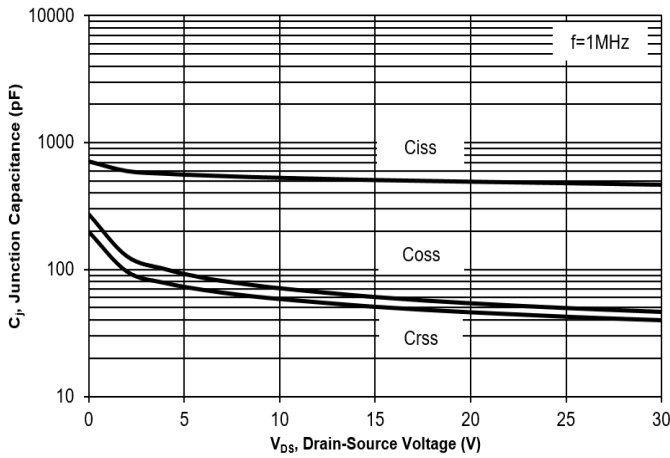


Fig. 8 Drain-Source Leakage Current vs. T_j

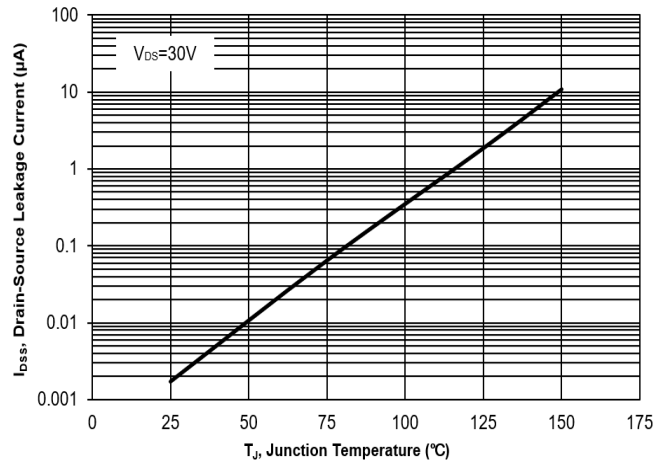


Fig. 9 $V_{(BR)DSS}$ vs. Junction Temperature

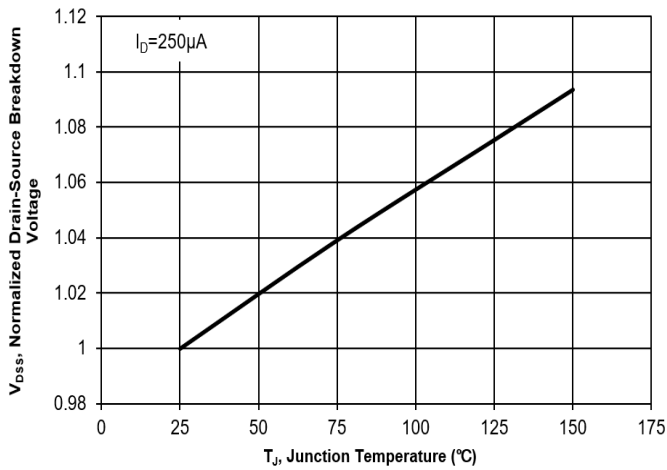


Fig. 10 Gate-Source Threshold Voltage vs. T_j

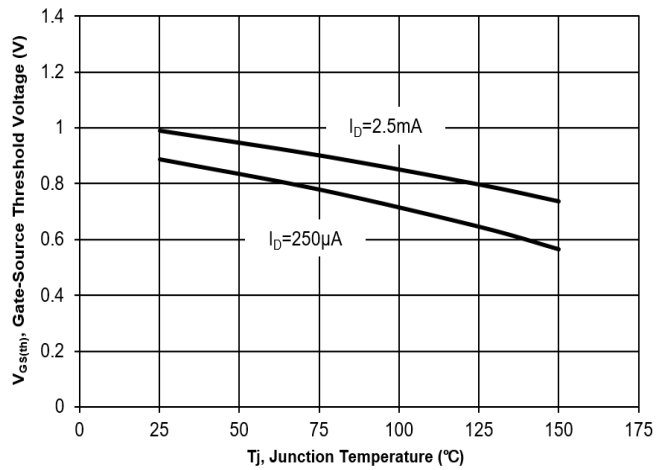
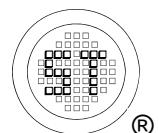
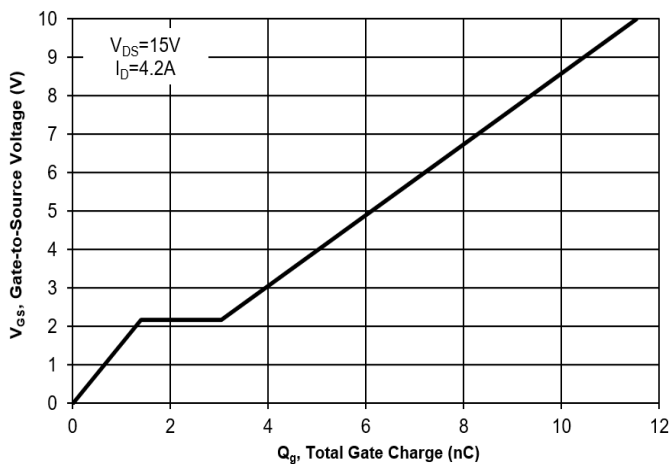


Fig. 11 Gate Charge



Test Circuits

Fig.1-1 Switching times test circuit

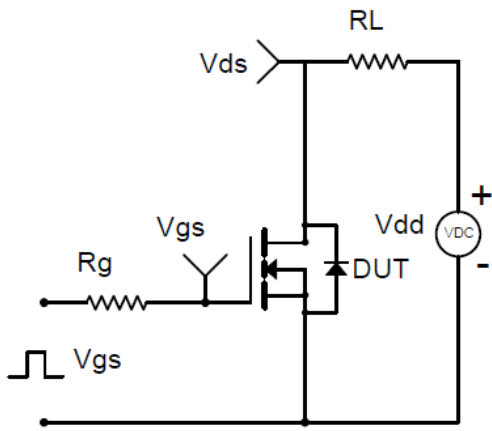


Fig.1-2 Switching Waveform

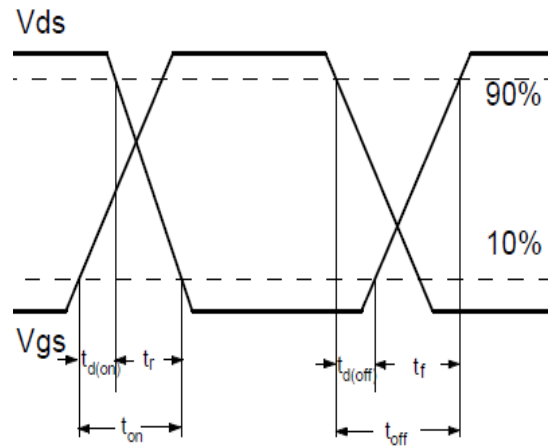


Fig.2-1 Gate charge test circuit

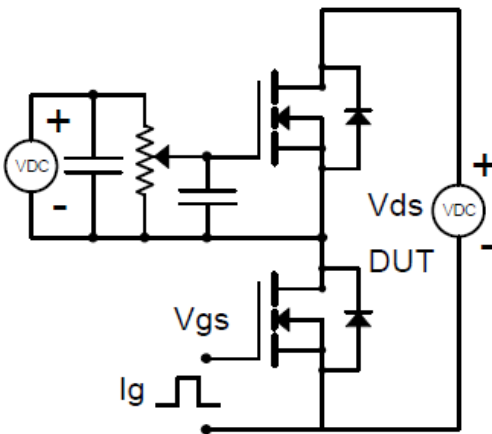
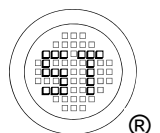
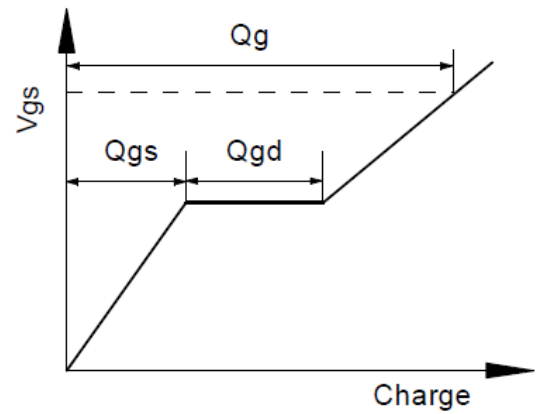


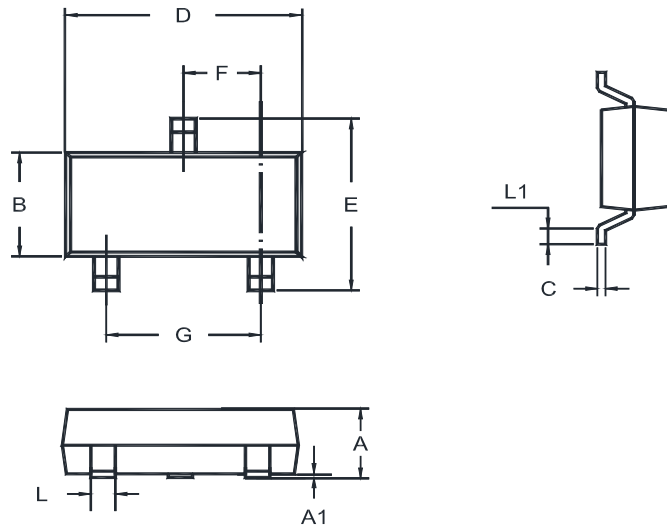
Fig.2-2 Gate charge waveform



MMFTN3400

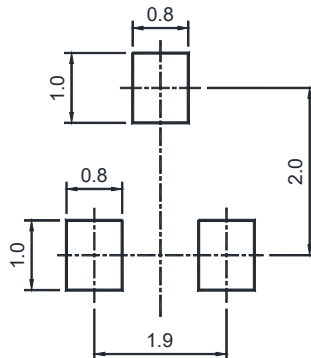
Package Outline (Dimensions in mm)

SOT-23



Unit	A	A1	B	C	D	E	F	G	L	L1
mm	1.20	0.100	1.40	0.19	3.04	2.6	1.02	2.04	0.51	0.2
	0.89	0.013	1.20	0.08	2.80	2.2	0.89	1.78	0.37	MIN

Recommended Soldering Footprint



Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
SOT-23	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000

Marking information

- " P3 " = Part No.
 - " YM " = Date Code Marking
 - " Y " = Year
 - " M " = Month
- Font type: Arial

